

## **Description**

The IPD050N03LG uses advanced trench technology

to provide excellent R<sub>DS(ON)</sub>, low gate charge and

operation with gate voltages as low as 4.5V. This

device is suitable for use as a

Battery protection or in other Switching application.



#### TO-252-2L

#### **General Features**

 $V_{DS} = 30V I_{D} = 100 A$ 

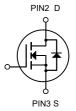
 $R_{DS(ON)} < 5m\Omega$  @  $V_{GS}=10V$ 

## **Application**

Battery protection

Load switch

Uninterruptible power supply



N-Channel MOSFET

# **Package Marking and Ordering Information**

Product ID	Pack	Brand	Qty(PCS)
IPD050N03LG	TO-252-2L	HXY MOSFET	2500

### Absolute Maximum Ratings (T<sub>c</sub>=25 ℃ unless otherwise noted)

Symbol	Parameter	Rating	Units
VDS	Drain- Source Voltage	30	V
VGS	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>C</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	100	Α
I <sub>D</sub> @T <sub>C</sub> =100°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	57	Α
Ірм	Pulsed Drain Current <sup>2</sup>	160	Α
EAS	Single Pulse Avalanche Energy <sup>3</sup>	115.2	mJ
las	Avalanche Current	48	Α
P <sub>D</sub> @T <sub>C</sub> =25°C	Total Power Dissipation <sup>4</sup>	53	W
Тѕтс	Storage Temperature Range	-55 to 175	°C
TJ	Operating Junction Temperature Range	-55 to 175	°C
R <sub>θ</sub> JA	Thermal Resistance Junction-ambient (Steady State) <sup>1</sup>		
Reja	Thermal Resistance Junction-Ambient ¹ (t ≤10s)		°C/W
R <sub>θ</sub> Jc	Thermal Resistance Junction-Case <sup>1</sup>	2.8	°C/W



# Electrical Characteristics (T<sub>J</sub>=25°C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BVpss	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA				V
△BVɒss/△Tɹ	BVDSS Temperature Coefficient	·		0.028		V/°C
.Rds(on)		V <sub>GS</sub> =10V , I <sub>D</sub> =30A		3.8	5.5	
.TADS(UN)	Static Drain-Source On- Resistance <sup>2</sup>	V <sub>GS</sub> =4.5V , I <sub>D</sub> =15A		7.5	9	mΩ
V <sub>G</sub> S(th)	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	1.0	1.5	2.5	V
$\triangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient			-6.16		mV/°C
		V <sub>DS</sub> =24V , V <sub>GS</sub> =0V ,			1	
IDSS	Drain-Source Leakage Current	T <sub>J</sub> =25°C V <sub>DS</sub> =24V , V <sub>GS</sub> =0V , T <sub>J</sub> =55°C			5	uA
Igss	Gate-Source Leakage Current	$V_{GS}$ = $\pm 20V$ , $V_{DS}$ = $0V$			±100	nA
gfs	Forward Transconductance	Forward Transconductance V <sub>DS</sub> =5V , I <sub>D</sub> =30A		22		S
R <sub>g</sub>	Gate Resistance	Gate Resistance V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz		1.7	3.4	Ω
Qg	Total Gate Charge (4.5V)			20		nC
Q <sub>gs</sub>	Gate-Source Charge	V <sub>DS</sub> =15V , V <sub>GS</sub> =4.5V , I <sub>D</sub> =15A		7.6		
Q <sub>gd</sub>	Gate-Drain Charge			7.2		
T <sub>d(on)</sub>	Turn-On Delay Time			7.8		ns
Tr	Rise Time	V <sub>DD</sub> =15V , V <sub>GS</sub> =10V ,		15		
T <sub>d</sub> (off)	Turn-Off Delay Time	-R <sub>G</sub> =3.3 -I <sub>D</sub> =15A		37.3		
T <sub>f</sub>	Fall Time	-1D-13A		10.6		
C <sub>iss</sub>	Input Capacitance			2295		
Coss	Output Capacitance	V <sub>DS</sub> =15V , V <sub>GS</sub> =0V , f=1MHz		267		pF
Crss	Reverse Transfer Capacitance	11- 11VII 12		210		
Is	Continuous Source Current <sup>1,5</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force			80	Α
Ism	Pulsed Source Current <sup>2,5</sup>	Current			160	Α
Vsp	Diode Forward Voltage <sup>2</sup>	Diode Forward Voltage <sup>2</sup> V <sub>GS</sub> =0V , I <sub>S</sub> =1A , T <sub>J</sub> =25°C			1	V
t <sub>rr</sub>	Reverse Recovery Time	IF=30A , dI/dt=100A/μs ,		14		nS
Qrr	Reverse Recovery Charge	T <sub>J</sub> =25°C		5		nC

#### Note:

<sup>1.</sup>The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.

<sup>2.</sup>The data tested by pulsed , pulse width .The EAS data shows Max. rating .

<sup>3.</sup> The test cond  $\!\leq$  300us , duty cycle ition is V\_DD=25  $\!\leq$  V,V 2%GS =10V,L=0.1mH,I\_AS=53.8A

<sup>4.</sup>The power dissipation is limited by 175°C junction temperature

<sup>5.</sup>The data is theoretically the same as ID and IDM, in real applications, should be limited by total power dissipation.



### **Typical Characteristics**

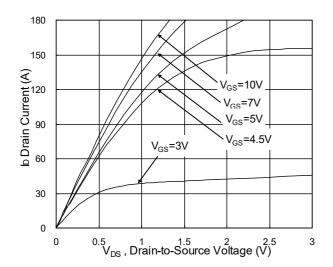


Fig.1 Typical Output Characteristics

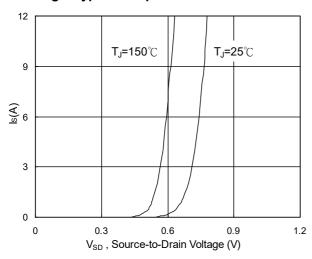


Fig.3 Forward Characteristics of Reverse

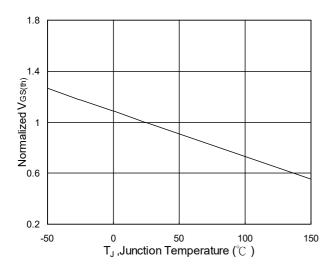


Fig.5 Normalized  $V_{\text{GS(th)}}$  vs.  $T_{\text{J}}$ 

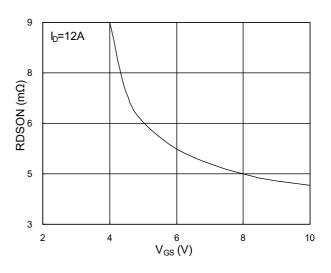


Fig.2 On-Resistance vs. G-S Voltage

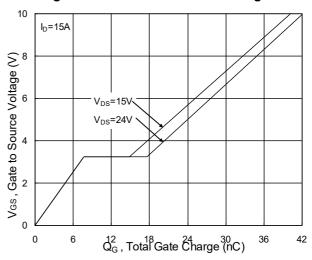


Fig.4 Gate-Charge Characteristics

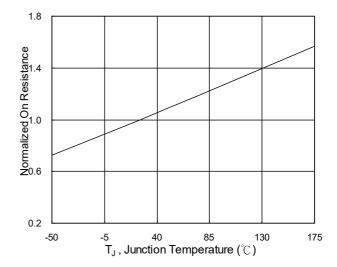
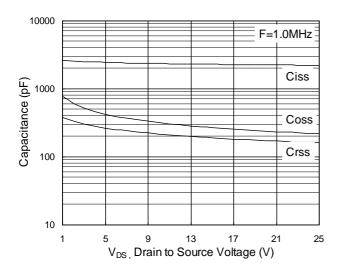


Fig.6 Normalized R<sub>DSON</sub> vs. T<sub>J</sub>



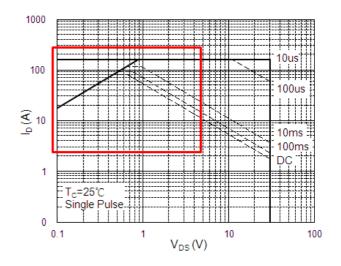


Fig.7 Capacitance

Fig.8 Safe Operating Area

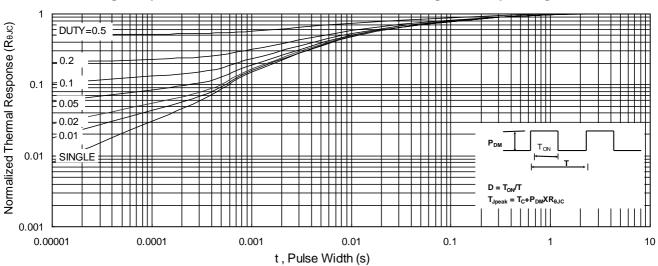


Fig.9 Normalized Maximum Transient Thermal Impedance

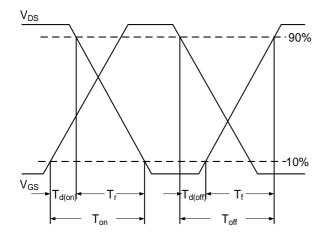


Fig.10 Switching Time Waveform

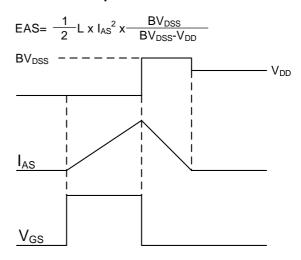
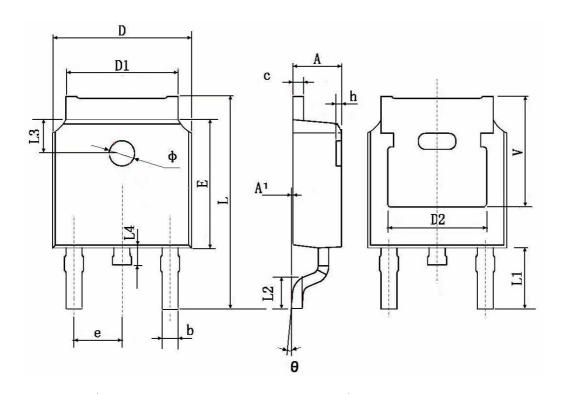


Fig.11 Unclamped Inductive Switching Waveform



# **TO-252-2L Package Information**



Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min.	Max.	Min.	Max.	
А	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
b	0.660	0.860	0.026	0.034	
С	0.460	0.580	0.018	0.023	
D	6.500	6.700	0.256	0.264	
D1	5.100	5.460	0.201	0.215	
D2	0.483 TYP.		0.190 TYP.		
Е	6.000	6.200	0.236	0.244	
е	2.186	2.386	0.086	0.094	
L	9.800	10.400	0.386	0.409	
L1	2.900 TYP.		0.114 TYP.		
L2	1.400	1.700	0.055	0.067	
L3	1.600 TYP.		0.063 TYP.		
L4	0.600	1.000	0.024	0.039	
Ф	1.100	1.300	0.043	0.051	
θ	0°	8°	0°	8°	
h	0.000	0.300	0.000	0.012	
V	5.350 TYP.		0.211	0.211 TYP.	

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